

What is claimed is:

1. A process for preparing a cold seal adhesive comprising the steps of:
  - a) providing a curable composition comprising:
    - i) from 30 to 90 weight % of at least one ethylenically unsaturated compound selected from the group consisting of ethylenically unsaturated monomers and ethylenically unsaturated oligomers;
    - ii) from 10 to 50 weight % of at least one liquid elastomer; and
    - iii) from 0 to 60 weight % of at least one tackifier;wherein all weight % are based on total weight of said curable composition; and
  - b) subjecting said curable composition to electron beam radiation to provide said cold seal adhesive.
2. The process according to claim 1 wherein said cold seal adhesive has a glass transition temperature of  $-30^{\circ}\text{C}$  or less.
3. The process according to claim 1 wherein said curable composition comprises from 20 to 60 weight % of said at least one tackifier.
4. The process according to claim 1 wherein said curable composition is substantially free of photoinitiator.
5. A cold seal adhesive prepared by the polymerization of a curable composition comprising:
  - a) from 30 to 90 weight % of at least one ethylenically unsaturated compound selected from the group consisting of ethylenically unsaturated monomers and ethylenically unsaturated oligomers;

b) from 10 to 50 weight % of at least one liquid elastomer selected from the group consisting of polyisoprenes, polybutadienes, and polyurethanes; and

c) from 0 to 60 weight % of at least one tackifier;

wherein all weight % are based on total weight of said curable composition; and wherein said curable composition is substantially free of photoinitiator.

6. The cold seal adhesive according to claim 5 having a glass transition temperature of -30°C or less.

7. The cold seal adhesive according to claim 5 wherein said curable composition comprises from 20 to 60 weight % of said at least one tackifier.

8. A curable composition comprising:

a) from 30 to 90 weight % of at least one ethylenically unsaturated compound selected from the group consisting of ethylenically unsaturated monomers and ethylenically unsaturated oligomers;

b) from 10 to 50 weight % of at least one liquid elastomer selected from the group consisting of polyisoprenes, polybutadienes, and polyurethanes; and

c) from 0 to 60 weight % of at least one tackifier;

wherein all weight % are based on total weight of said curable composition; and wherein said curable composition is substantially free of photoinitiator.

9. The curable composition according to claim 8 comprising from 20 to 60 weight % of said at least one tackifier.

10. The curable composition according to claim 8 wherein a cured polymer composition formed from said curable composition has a glass transition

temperature of  $-30^{\circ}\text{C}$  or less.